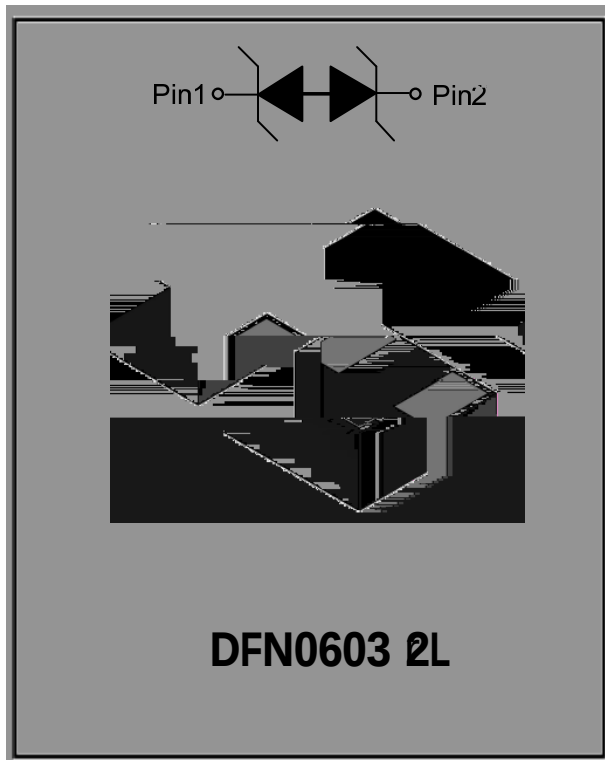


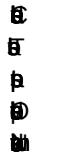
1- L pBiLED



Fa



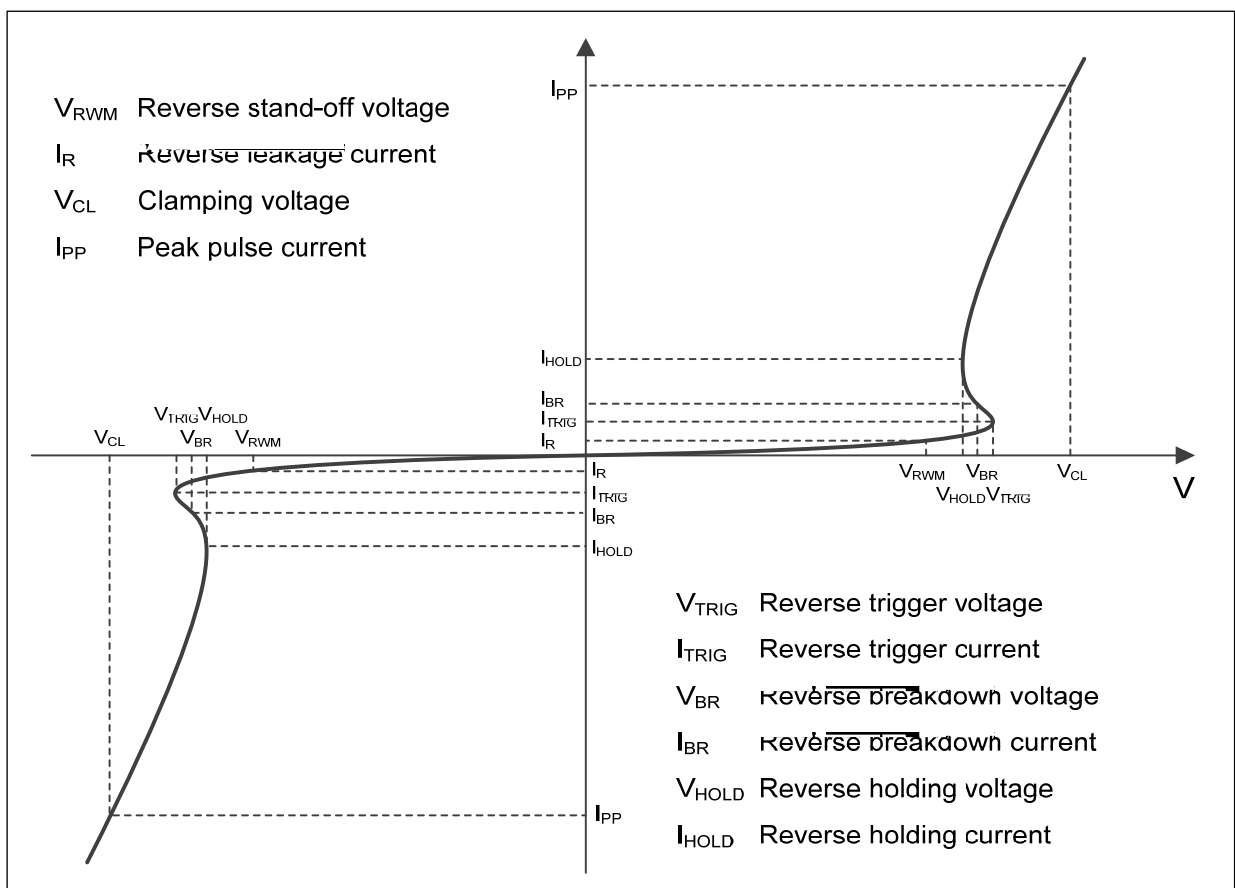
Ap



Mc



VD





ED50

L

BA

VA

ARMER	MO L	Rating	W
P_{p}	P_{p}	2	W
I_{p}	I_{p}	6	A
	V_{B}	8	W
		8	W
T_{J}	T_{J}	2	$^{\circ}\text{C}$
T_{B}	T_{B}	8	$^{\circ}\text{C}$
T	T	8	$^{\circ}\text{C}$

VECh

T a

W

ARMER	W		M	P	M
V	V	V		8	
I	R	$A V$		0	
	V_{B}	$V I$	5		7
V	B	$V I$	5		7
¹⁾	V_{C}	$V I$		7	
¹⁾	R_{B}			0	
²⁾	V_{C}	$V V$		8	
³⁾	V_{C}	$V I$		6	7
		$V I$		8	8
		$V I$		8	9
β	C_{J}	βV		5	5
		βV		8	5

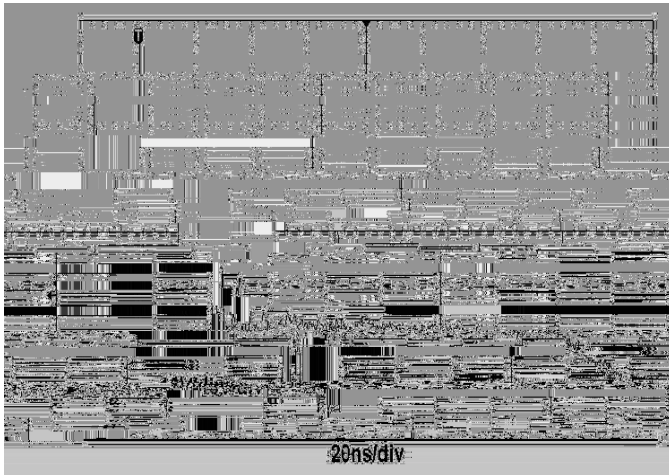
08 t p 10 10 10



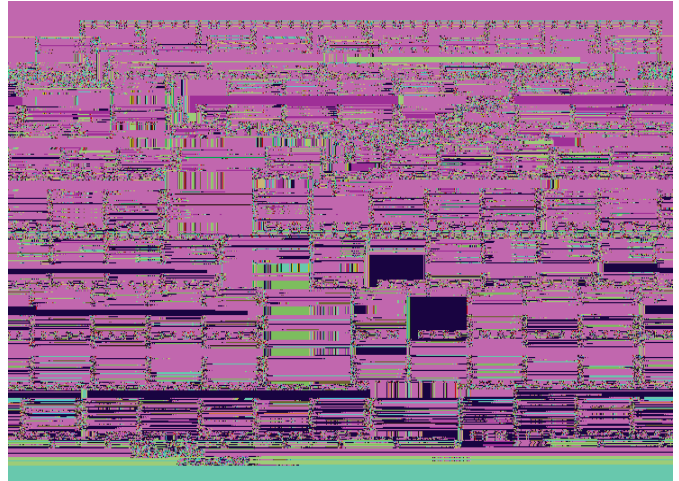
四

Contact discharge: Li^+ & S^{2-} Card EC61000 r

ESD clamping
(+8kV contact discharge per IEC61000 4 2)



ESD clamping
(-8kV contact discharge per IEC61000 4 2)



TLP Measurement

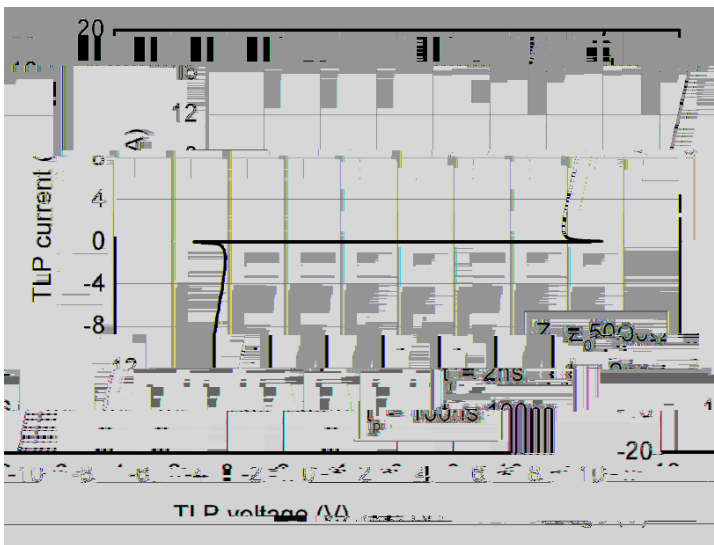
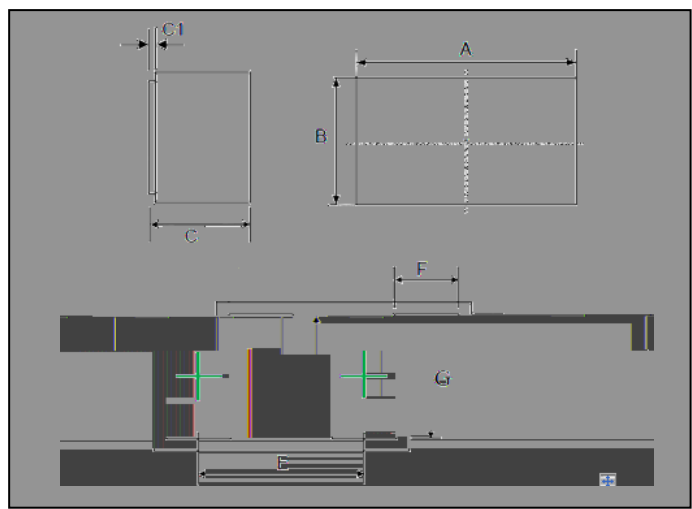




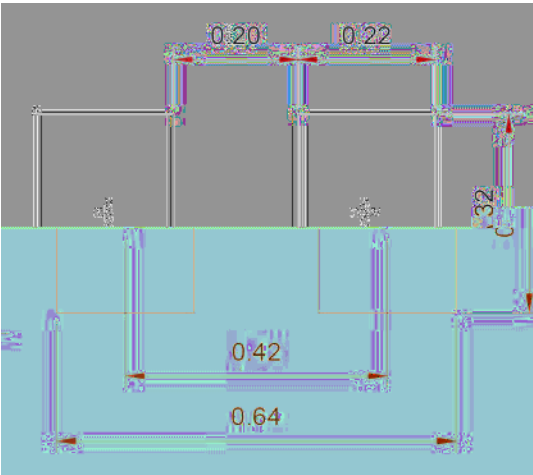
Figure 1



6 \ PERO	PLQ	PP	0 D
\$			
%			
&			
&			
(			
)			
*			

PP

Figure 2



Notes:
This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met



ED50

L

BA

Din